



Semiconductor Device Type: MUY (6QX) 008 UDFN 2x3x0.5mm NiPdAu				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			JEDEC 97 Product Marking and/or Pkg. Labeling e4		
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	(mg) Total	Mold Compound	% of Total Weight				
Silica, fused	60676-86-0	Mold Compound	61.155	4.831	611,550	5.37	Epoxy Resin (NLP # 500-033-5)	90.00	67.95			
Epoxy Resin (NLP # 500-033-5)	Trade Secret	Mold Compound	3.296	0.260	32,956				Silica, fused	60676-86-0	90.00	
Phenolic Resin	Trade Secret	Mold Compound	3.296	0.260	32,956				Trade Secret	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.204	0.016	2,039				Phenolic Resin	Trade Secret	4.85	
Copper	7440-50-8	Lead Frame	20.779	1.642	207,786				Carbon Black	1333-86-4	0.30	
Tin	7440-31-5	Lead Frame	0.053	0.004	533	Total			100.00			
Silver	7440-22-4	Lead Frame	0.406	0.032	4,063	1.69	(mg) Total	Lead Frame	% of Total Weight	21.33		
Zinc	7440-66-6	Lead Frame	0.038	0.003	384	Copper	7440-50-8	97.42				
Chromium	7440-47-3	Lead Frame	0.053	0.004	533				Tin	7440-31-5	0.25	
Silver	7440-22-4	Die Attach	1.911	0.151	19,110				Silver	7440-22-4	1.91	
Acrylate resins Proprietary	Trade Secret	Die Attach	0.441	0.035	4,410				Zinc	7440-66-6	0.18	
Treated silica	Trade Secret	Die Attach	0.049	0.004	490				Chromium	7440-47-3	0.25	
Heterocyclic organic compound	Trade Secret	Die Attach	0.049	0.004	490	Total			100.00			
Silicon	7440-21-3	Chip (Die)	7.350	0.581	73,500	0.19	(mg) Total	Die Attach	% of Total Weight	2.45		
Gold	7440-57-5	Wire Bond	0.750	0.059	7,500	Silver	7440-22-4	78				
Nickel	7440-02-0	Plating on external leads (pins)	0.163	0.013	1,627				Acrylate resins Proprietary	Trade Secret	18	
Palladium	7440-05-3	Plating on external leads (pins)	0.005	0.000	55				Treated silica	Trade Secret	2	
JGPSSI (D02) (Gold)	7440-57-5	Plating on external leads (pins)	0.002	0.000	18				Heterocyclic organic compound	Trade Secret	2	
TOTALS:			100.000	7.900	1,000,000				Total			100.00
0.0079 g Total Mass						0.58	Total (mg)	Chip (Die)	% of Total Weight	7.35		
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)						Doped Silicon		7440-21-3	100			
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.						Total			100.00			
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.						0.06	(mg) Total	Wire Bond	% of Total Weight	0.75		
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offering/industries/chemicals/plastics/						Doped Gold		7440-57-5	100			
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.						Total			100.00			
Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in their original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not include trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts.						0.01	(mg) Total	Plating on external leads (pins)	% of Total Weight	0.17		
Microchip Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited product warranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's quotations, sales order acknowledgement, and invoices.						Nickel	7440-02-0	95.73				
Microchip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or otherwise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or of this Certificate of Compliance for semiconductor products.									Palladium	7440-05-3	3.23	
Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table									Gold	7440-57-5	1.04	
						Total			100.00			
						7.9						